

IEEE TRANSACTIONS ON DEVICE AND MATERIALS RELIABILITY

A PUBLICATION OF THE IEEE ELECTRON DEVICES SOCIETY AND THE IEEE RELIABILITY SOCIETY
www.ieee.org/ieeexplore

JUNE 2012

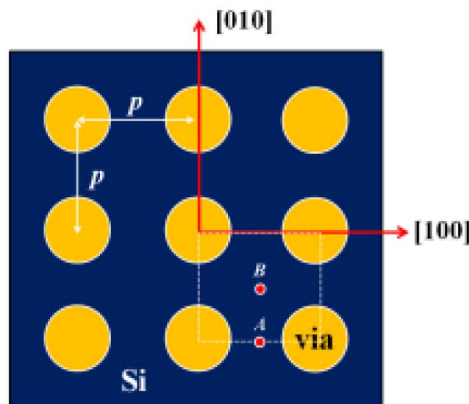
VOLUME 12

NUMBER 2

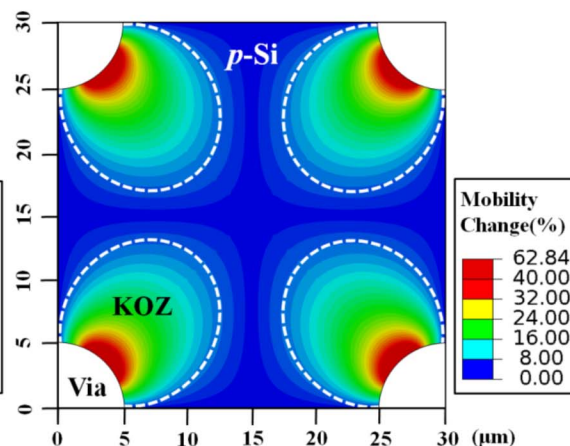
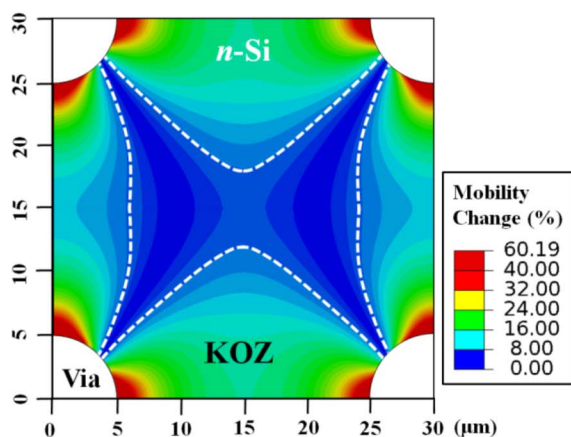
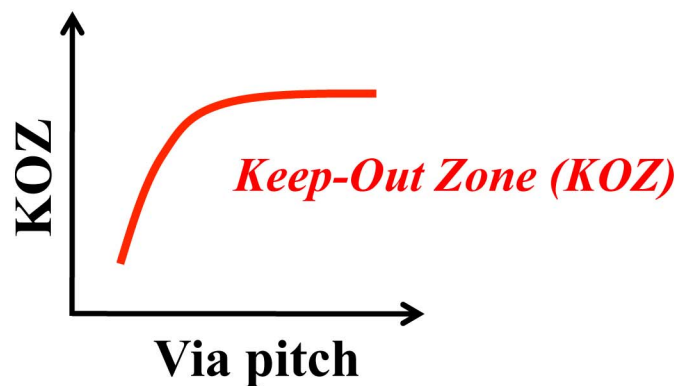
ITDMA2

(ISSN 1530-4388)

SPECIAL SECTION ON MATERIALS, PROCESSING, AND
RELIABILITY OF 3-D INTERCONNECTS



TSV array



Effect of stress interaction on KOZ